

Title (en)

Device and process for grinding and/or polishing surfaces

Title (de)

Vorrichtung und Verfahren zum Schleifen und/oder Polieren von Oberflächen

Title (fr)

Dispositif et procédé de meulage et/ou polissage de surfaces

Publication

EP 1618992 A1 20060125 (DE)

Application

EP 04017330 A 20040722

Priority

EP 04017330 A 20040722

Abstract (en)

The grinding and/or polishing device (1) grinds material from a surface (S) of a workpiece (2), grinding it with abrasive particles (5) supplied in a liquid (3). The grinding device includes a device for setting the gas content in the fluid, in particular, to remove a gas (4) usually air, from the fluid; this may include a pump (7).

IPC 8 full level

B24C 1/08 (2006.01)

CPC (source: EP)

B24C 1/04 (2013.01); **B24C 1/08** (2013.01); **B24C 7/0007** (2013.01); **B24C 7/0084** (2013.01); **B24C 11/005** (2013.01)

Citation (search report)

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